

DP-311030

METHOD OF MANUFACTURING A SEALED ELECTRONIC MODULE

Abstract of the Disclosure

A sealed electronic module is manufactured by forming a housing that is open at one end, dispensing a first quantity of potting material into the housing via the open end, inserting a circuit board and electrical connector assembly into the housing so that the inboard end of the circuit board is immersed in the potting material, and dispensing a second quantity of potting material into an area bridging the connector assembly and the housing. When cured, the first quantity of potting material attaches the inboard end of the circuit board to the housing, and the second quantity of potting material attaches the connector to the housing and environmentally seals the module.